

NTR2101P

Small Signal MOSFET

–8.0 V, –3.7 A, Single P–Channel, SOT–23

Features

- Leading Trench Technology for Low $R_{DS(on)}$
- –1.8 V Rated for Low Voltage Gate Drive
- SOT–23 Surface Mount for Small Footprint (3 x 3 mm)
- This is a Pb–Free Device

Applications

- High Side Load Switch
- DC–DC Conversion
- Cell Phone, Notebook, PDAs, etc.

MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise stated)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V_{DSS}	−8.0	V
Gate-to-Source Voltage			V_{GS}	±8.0	V
Continuous Drain Current (Note 1)	$t \leq 5 \text{ s}$	$T_A = 25^\circ\text{C}$	I_D	−3.7	A
		$T_A = 70^\circ\text{C}$		−3.0	
Power Dissipation (Note 1)	$t \leq 5 \text{ s}$		P_D	0.96	W
Pulsed Drain Current	$t_p = 10 \text{ }\mu\text{s}$		I_{DM}	−11	A
Operating Junction and Storage Temperature			T_J , T_{STG}	−55 to 150	$^\circ\text{C}$
Source Current (Body Diode)			I_S	−1.2	A
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			T_L	260	$^\circ\text{C}$

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction–to–Ambient – Steady State	$R_{\theta JA}$	160	$^\circ\text{C}/\text{W}$
Junction–to–Ambient – $t \leq 5$ s	$R_{\theta JA}$	130	$^\circ\text{C}/\text{W}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

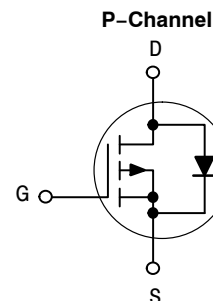
1. Surface mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [1 oz] including traces).



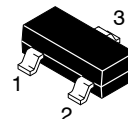
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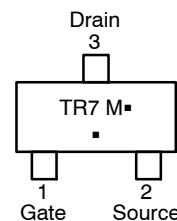
$V_{(BR)DS}$	$R_{DS(on)}$ Typ	I_D Max
–8.0 V	39 m Ω @ –4.5 V	–3.7 A
	52 m Ω @ –2.5 V	
	79 m Ω @ –1.8 V	



MARKING DIAGRAM & PIN ASSIGNMENT



SOT–23
CASE 318
STYLE 21



TR7 = Specific Device Code
M = Date Code*
▪ = Pb–Free Package

(Note: Microdot may be in either location)

*Date Code orientation may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping†
NTR2101PT1G	SOT–23 (Pb–Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

NTR2101P

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise stated)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = -250\text{ }\mu\text{A}$	-8.0			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	$V_{(BR)DSS}/T_J$			10		mV/ $^\circ\text{C}$
Zero Gate Voltage Drain Current	I_{DSS}	$V_{GS} = 0\text{ V}, V_{DS} = -6.4\text{ V}$	$T_J = 25^\circ\text{C}$		-1.0	μA
			$T_J = 125^\circ\text{C}$		-100	
Gate-to-Source Leakage Current	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = \pm 8.0\text{ V}$			± 100	nA

ON CHARACTERISTICS (Note 2)

Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = -250\text{ }\mu\text{A}$	-0.40		-1.0	V
Negative Threshold Temperature Coefficient	$V_{GS(TH)}/T_J$			2.7		mV/ $^\circ\text{C}$
Drain-to-Source On Resistance	$R_{DS(on)}$	$V_{GS} = -4.5\text{ V}, I_D = -3.5\text{ A}$		39	52	m Ω
		$V_{GS} = -2.5\text{ V}, I_D = -3.0\text{ A}$		52	72	
		$V_{GS} = -1.8\text{ V}, I_D = -2.0\text{ A}$		79	120	
Forward Transconductance	g_{FS}	$V_{GS} = -5.0\text{ V}, I_D = -3.5\text{ A}$		9.0		S

CHARGES AND CAPACITANCES

Input Capacitance	C_{ISS}	$V_{GS} = 0\text{ V}, f = 1.0\text{ MHz}, V_{DS} = -4.0\text{ V}$		1173		pF
Output Capacitance	C_{OSS}			289		
Reverse Transfer Capacitance	C_{RSS}			218		
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = -4.5\text{ V}, V_{DS} = -4.0\text{ V}, I_D = -3.5\text{ A}$		12	15	nC
Gate-to-Source Charge	Q_{GS}			3.8		
Gate-to-Drain Charge	Q_{GD}			2.5		

SWITCHING CHARACTERISTICS (Note 3)

Turn-On Delay Time	$t_{d(on)}$	$V_{GS} = -4.5\text{ V}, V_{DD} = -4.0\text{ V}, I_D = -1.2\text{ A}, R_G = 6.0\text{ }\Omega$		7.4	15	ns
Rise Time	t_r			15.75	25	
Turn-Off Delay Time	$t_{d(off)}$			38	58	
Fall Time	t_f			31	51	

DRAIN-SOURCE DIODE CHARACTERISTICS

Forward Diode Voltage	V_{SD}	$V_{GS} = 0\text{ V}, I_S = -1.2\text{ A}$	$T_J = 25^\circ\text{C}$		-0.73	-1.2	V
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- Pulse Test: pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.
- Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS

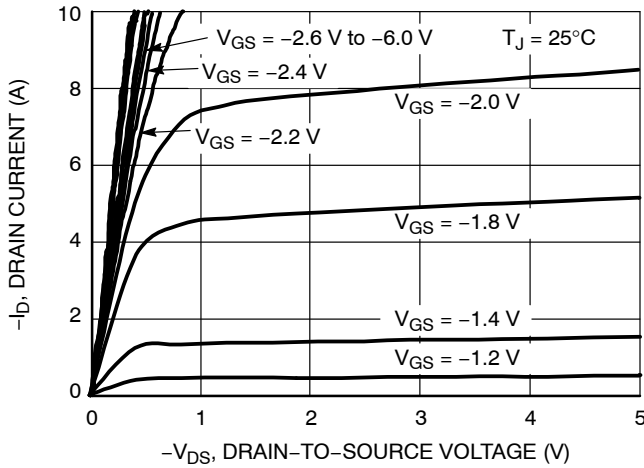


Figure 1. On-Region Characteristics

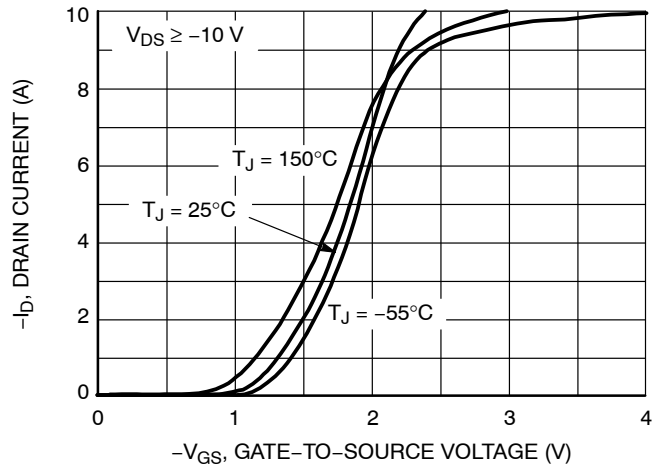


Figure 2. Transfer Characteristics

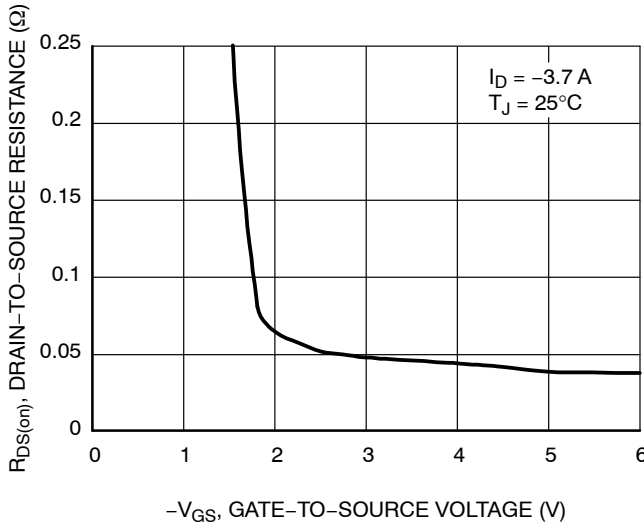


Figure 3. On-Resistance versus Gate-to-Source Voltage

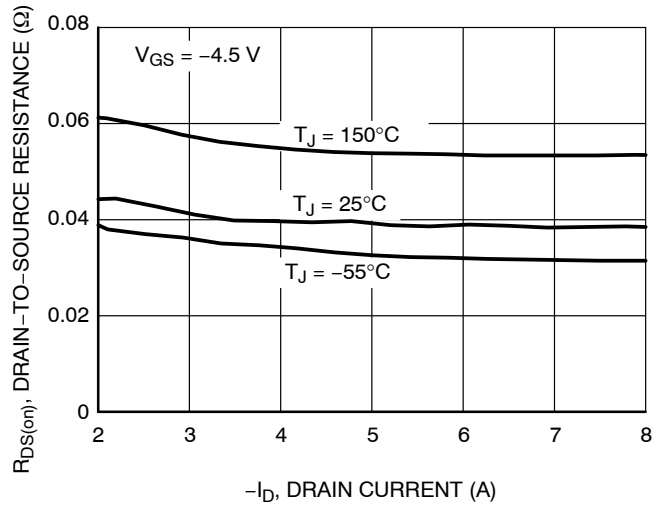


Figure 4. On-Resistance versus Drain Current and Gate Voltage

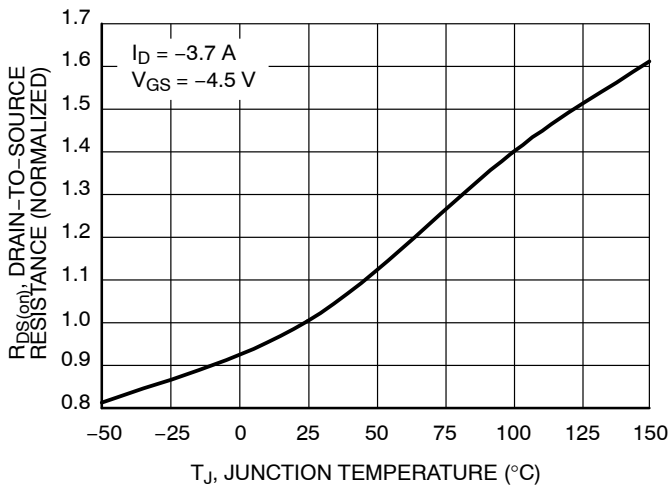


Figure 5. On-Resistance Variation with Temperature

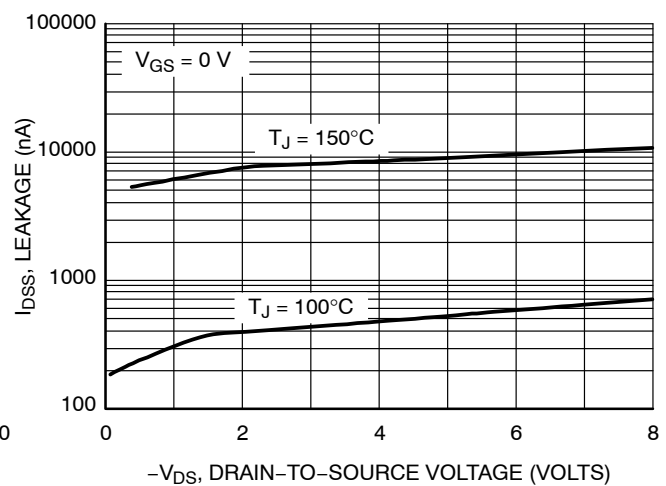
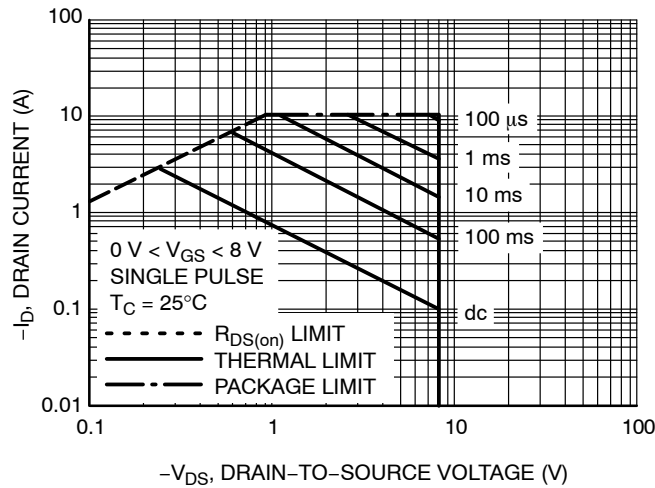
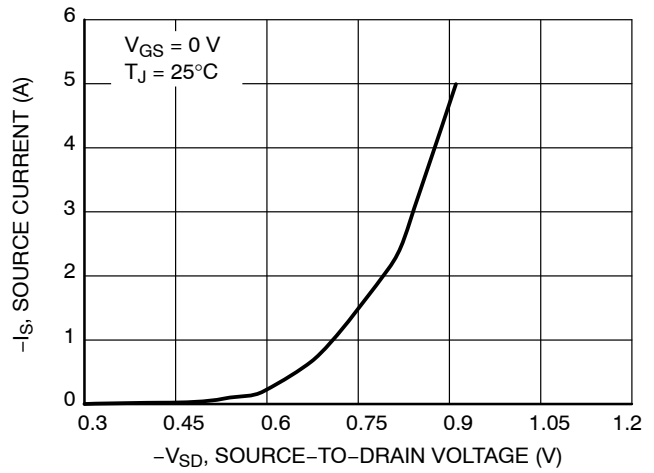
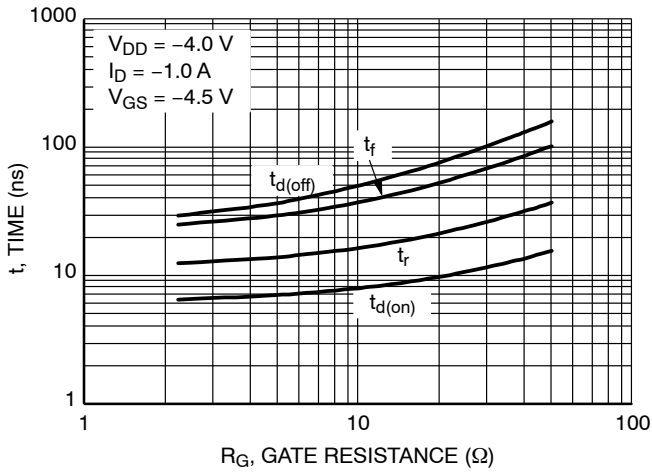
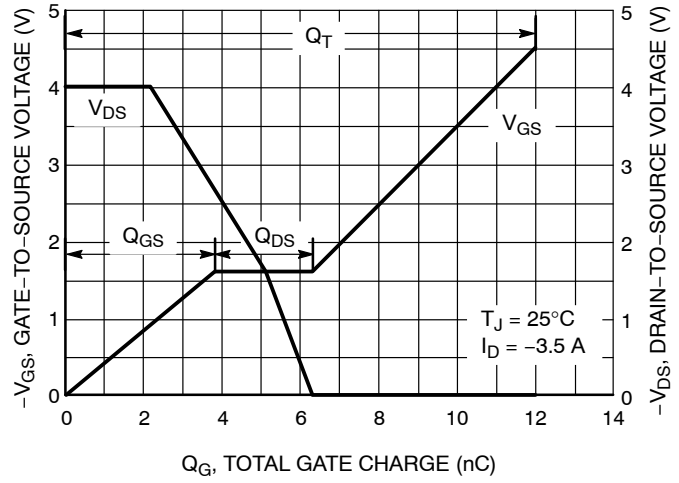
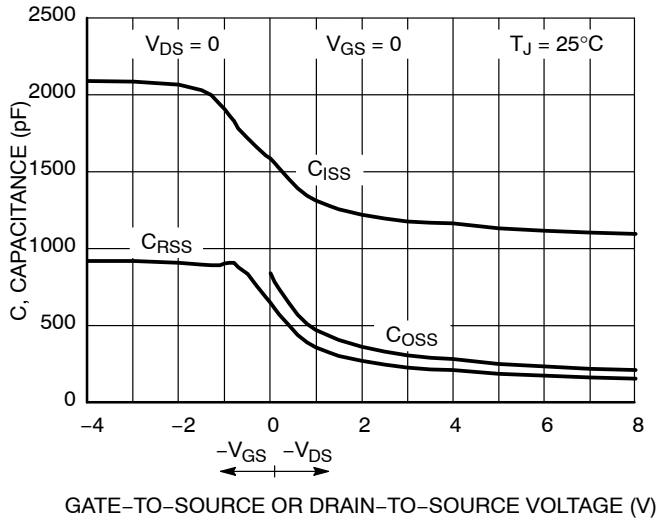


Figure 6. Drain-to-Source Leakage Current versus Voltage

TYPICAL CHARACTERISTICS



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TYPICAL CHARACTERISTICS

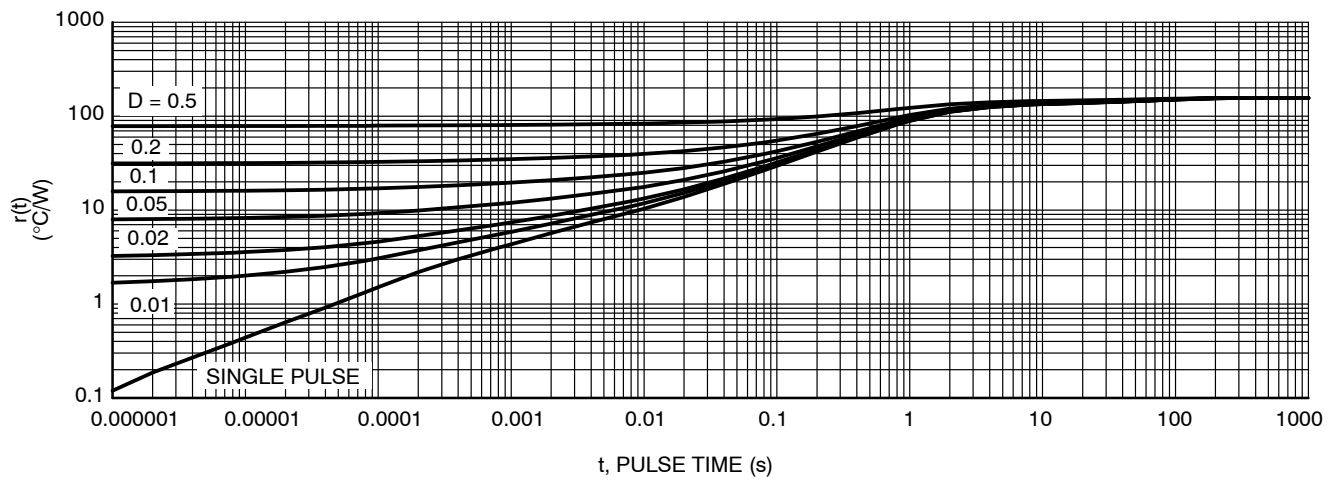
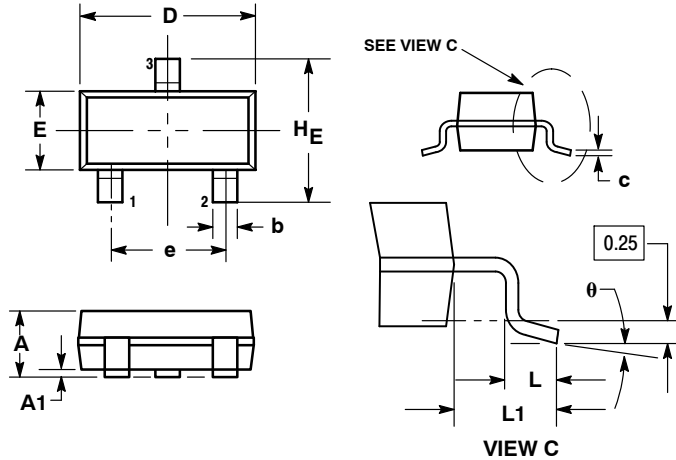


Figure 12. Thermal Response

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PACKAGE DIMENSIONS

SOT-23 (TO-236)
CASE 318-08
ISSUE AP



NOTES:

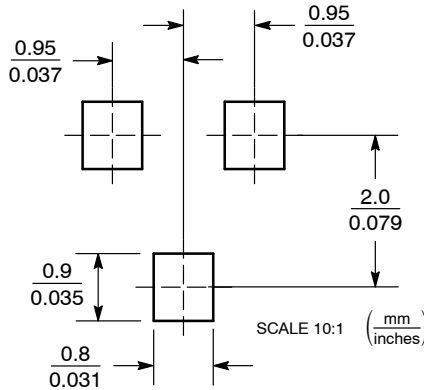
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
c	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104
θ	0°	---	10°	0°	---	10°

STYLE 21:

- PIN 1. GATE
- SOURCE
- DRAIN

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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